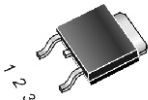


Description

Passivated high commutation triacs in a plastic envelope intended for use in circuits where high static and dynamic dV/dt and high dI/dt can occur. These devices will commute the full rated ms current at the maximum rated junction temperature without the aid of a snubber.

Symbol		Simplified outline	
		 TO-252	
Pin	Description		
1	Main terminal 1 (T1)		
2	Main terminal 2 (T2)		
3	gate (G)		
TAB	Main terminal 2 (T2)		

Applications:

- ◆ Motor control
- ◆ Industrial and domestic lighting
- ◆ Heating
- ◆ Static switching

Features

- ◆ Blocking voltage to 800 V
- ◆ On-state RMS current to 8 A

SYMBOL	PARAMETER	Value	Unit
V_{DRM}	Repetitive peak off-state voltages	800	V
$I_T (RMS)$	RMS on-state current (full sine wave)	8	A
I_{TSM}	Non-repetitive peak on-state current (full cycle, T_j initial=25°C)	84	A

SYMBOL	PARAMETER	CONDITIONS	MIN	TYP	MAX	UNIT
$R_{th(j-c)}$	Junction to case(AC)		-	1.6	-	°C/W
$R_{th(j-a)}$	Junction to ambient		-	70	-	°C/W



HP8Q80DS

Three quadrant triacs

HAOPIN MICROELECTRONICS CO.,LTD.

Limiting values in accordance with the Maximum system(IEC 134)

SYMBOL	PARAMETER	CONDITIONS			MIN	Value	UNIT
V _{DRM} /V _{RRM}	Repetitive peak off-state Voltages				-	800	V
I _{T(RMS)}	RMS on-state current	Full sine wave;T _c =110℃			-	8	A
I _{TSM}	Non repetitive surge peak on-state current	full cycle, Tj initial= 25 ℃	F=50Hz	t=20ms	-	80	A
			F=60Hz	t=16.7ms	-	84	A
I ² t	I ² t value for fusing	tp=10ms			-	36	A ² S
dI/dt	Critical rate of rise of on-state current	I _G =2x I _{GT} ,tr<=100ns	F=120Hz Tj=125℃		-	50	A/ μs
I _{GM}	Peak gate current		tp=20us	Tj=125℃	-	4	A
I _{DRM} I _{RRM}	V _{DRM} =V _{RRM}	Tj=25℃			-	5	μ A
		Tj=125℃			-	1	mA
P _{G(AV)}	Average gate power dissipation			Tj=125℃	-	1	W
T _{stg}	Storage junction temperature range				-40	150	℃
T _j	Operating junction temperature range				-40	125	℃

$T_j=25^{\circ}C$ unless otherwise stated

SYMBOL	PARAMETER	CONDITIONS	MIN	TYP	MAX	UNIT
Static characteristics						
$I_{GT}(1)$	V_{GT}	$V_D=12V$; $R_L=30\Omega$	-	-	10	mA
		I-II-III			1.3	V
I_L		$I_G=1.2 I_{GT}$	-	-	25	mA
		I-III	-	-	30	mA
$I_H(2)$	$I_T=100mA$		-	-	15	mA
V_{GD}	$V_D=V_{DRM}$ $R_L=3.3K\Omega$ $T_j=125^{\circ}C$		0.2	-	-	V
$dV/dt(2)$	$V_D=67\%V_{DRM}$ gate open; $T_j=125^{\circ}C$		40	-	-	V/ μ s
$(dI/dt)_c(2)$	$(dv/dt)_c=0.1V/ \mu$ S $T_j=125^{\circ}C$ $(dv/dt)_c=10V/ \mu$ S $T_j=125^{\circ}C$		5.4 2.8	-	-	V/ μ s

Dynamic Characteristics

$V_{TM}(2)$	$I_{TM}=11A$ tp=380 μ s	$T_j=25^{\circ}C$	-	-	1.55	V
$V_{to}(2)$ $R_d(2)$	Threshold voltage Dynamic resistance	$T_j=125^{\circ}C$ $T_j=125^{\circ}C$	-	-	0.85 50	V m Ω

Note1: minimum I_{GT} is guaranted at 5% of I_{GT} max.

Note2: for both polarities of A2 referenced to A1.

HAOPIN MICROELECTRONICS CO.,LTD.

Description

Fig. 1: Maximum power dissipation versus RMS on-state current (full cycle).

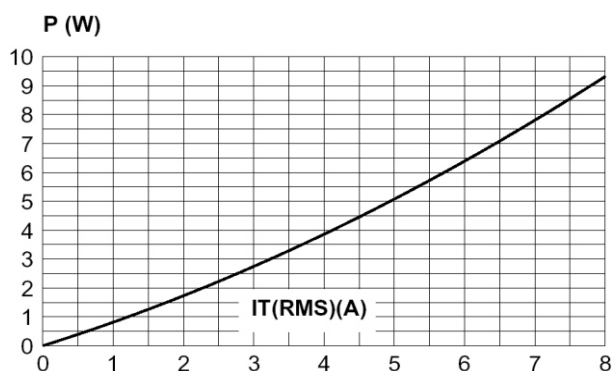


Fig. 2-1: RMS on-state current versus case temperature (full cycle).

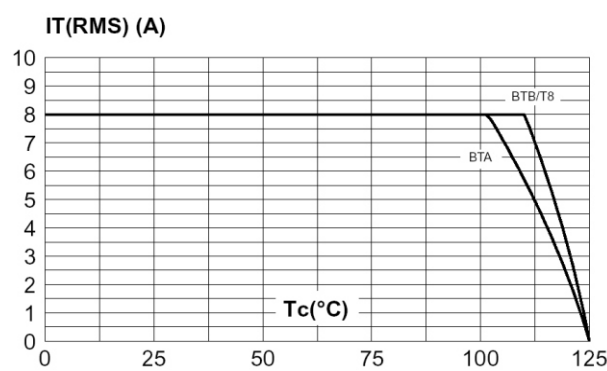


Fig. 2-2: RMS on-state current versus ambient temperature (printed circuit board FR4, copper thickness: 35μm), full cycle.

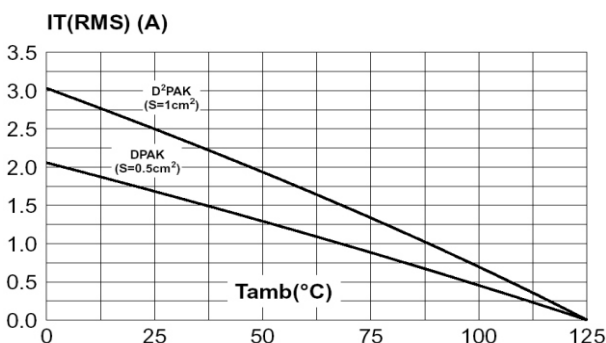


Fig. 3: Relative variation of thermal impedance versus pulse duration.

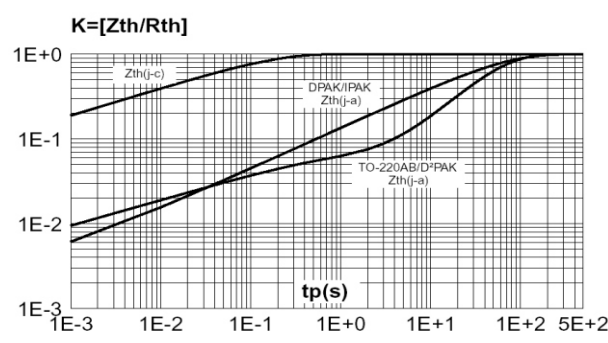


Fig. 4: On-state characteristics (maximum values).

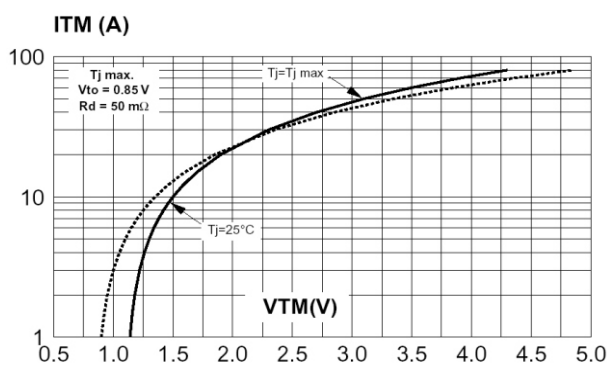
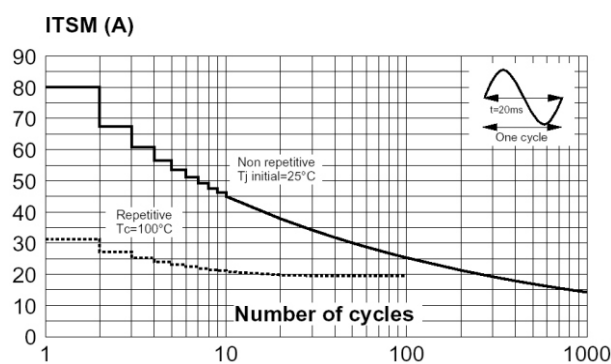


Fig. 5: Surge peak on-state current versus number of cycles.





HP8Q80DS

Three quadrant triacs

HAOPIN MICROELECTRONICS CO.,LTD.

Description

Fig. 6: Non-repetitive surge peak on-state current for a sinusoidal pulse with width $t_p < 10\text{ms}$, and corresponding value of I^2t .

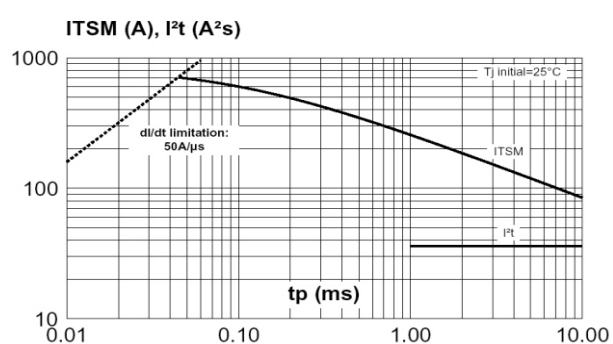


Fig. 7: Relative variation of gate trigger current, holding current and latching current versus junction temperature (typical values).

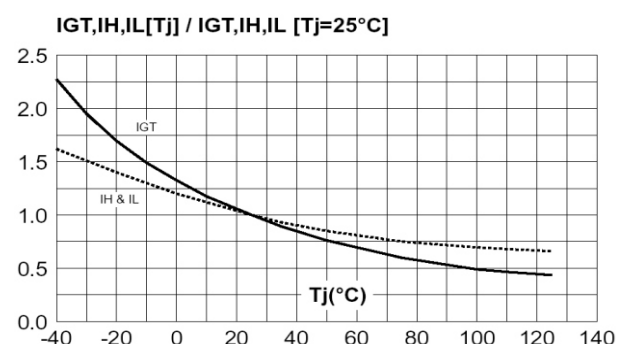


Fig. 8-1: Relative variation of critical rate of decrease of main current versus $(dV/dt)_c$ (typical values). Snubberless & Logic Level Types

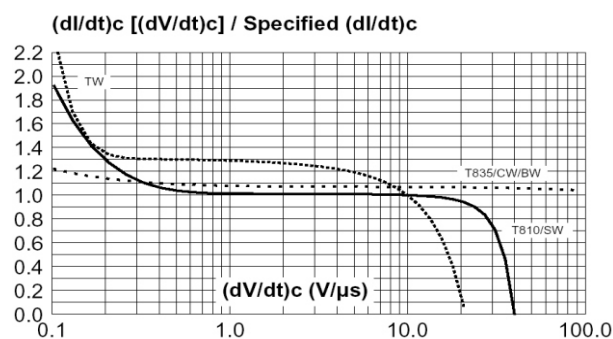


Fig. 8-2: Relative variation of critical rate of decrease of main current versus $(dV/dt)_c$ (typical values). Standard Types

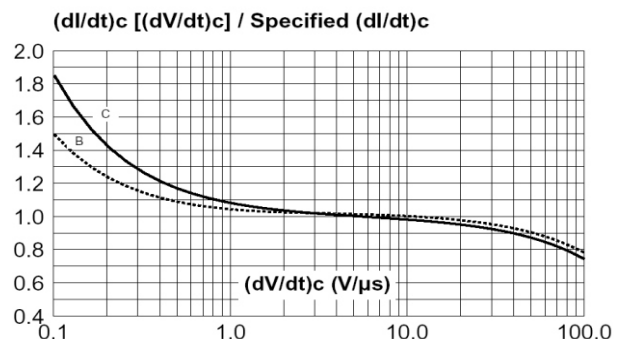


Fig. 9: Relative variation of critical rate of decrease of main current versus junction temperature.

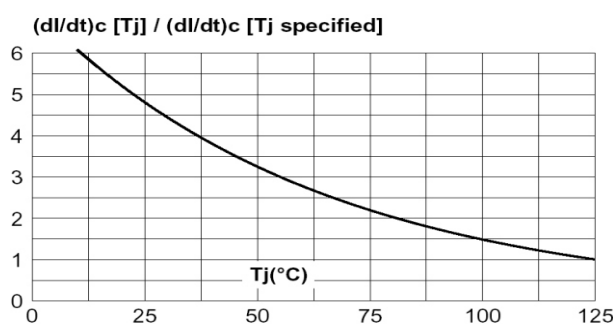
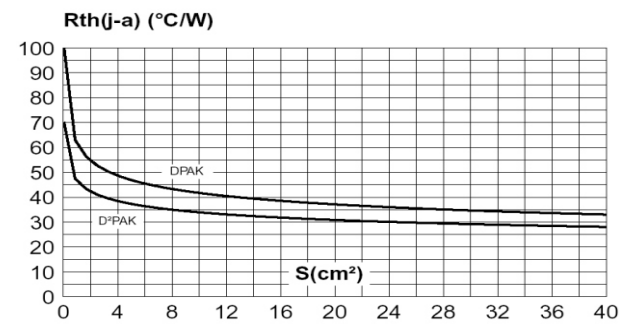


Fig. 10: DPAK and D²PAK Thermal resistance junction to ambient versus copper surface under tab (printed circuit board FR4, copper thickness: 35 μm).





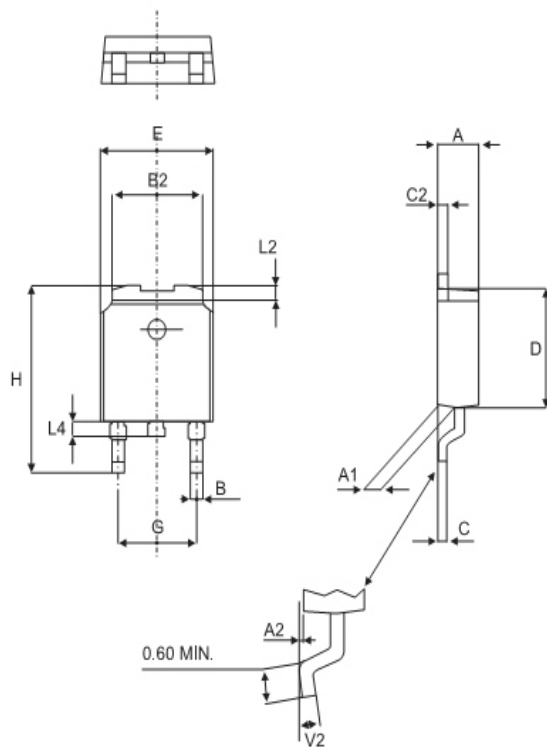
HP8Q80DS

Three quadrant triacs

HAOPIN MICROELECTRONICS CO.,LTD.

MECHANICAL DATA

Dimensions in mm
Net Mass: 0.3 g
TO-252



REF.	DIMENSIONS			
	Millimeters		Inches	
	Min.	Max	Min.	Max.
A	2.20	2.40	0.086	0.094
A1	0.90	1.10	0.035	0.043
A2	0.03	0.23	0.001	0.009
B	0.64	0.90	0.025	0.035
B2	5.20	5.40	0.204	0.212
C	0.45	0.60	0.017	0.023
C2	0.48	0.60	0.018	0.023
D	6.00	6.20	0.236	0.244
E	6.40	6.60	0.251	0.259
G	4.40	4.60	0.173	0.181
H	9.35	10.10	0.368	0.397
L2	0.80 typ.		0.031 typ.	
L4	0.60	1.00	0.023	0.039
R	0.2 typ.		0.007 typ.	
V2	0°	8°	0°	8°